

MB1-130-01-F-S-01-SL-N

MB1-130-01-F-S-01-SL

(1.00 mm) .0394"

MB1 SERIES

# MINI EDGE CARD SOCKET WITH GUIDES

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MB1](http://www.samtec.com?MB1)

**Insulator Material:**

Black LCP

**Contact Material:**

BeCu

**Plating:**

Sn or Au over

50 μ" (1.27 μm) Ni

**Current Rating:**

2.2 A per pin

(6 pins powered)

**Operating Temp Range:**

-55 °C to +125 °C

**Insertion Depth:**

(5.26 mm) .207" to

(6.10 mm) .240"

**RoHS Compliant:**

Yes

**Mates with:**

(0.80 mm) .031" PCB,

(1.60 mm) .062" PCB

## PROCESSING

**Lead-Free Solderable:**

Yes

**SMT Lead Coplanarity:**

(0.10 mm) .004" max (20-30)

(0.15 mm) .006" max (40-50)\*

\*(.004" stencil solution may be available; contact

IPG@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)

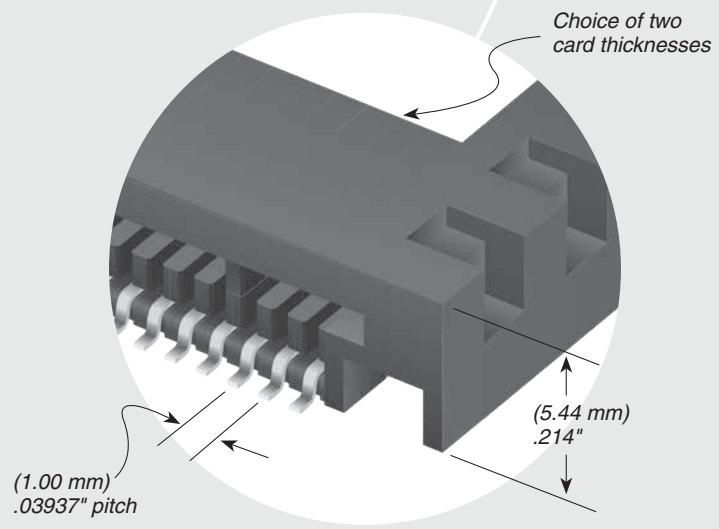


## ALSO AVAILABLE (MOQ Required)

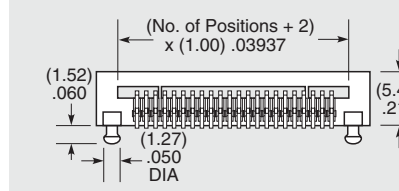
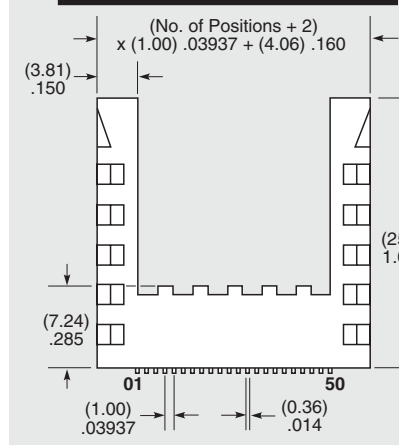
- Other platings

**Notes:**  
Patented

Some sizes, styles and options are non-standard, non-returnable.



**20, 30, 40, 50**



**PLATING OPTION**

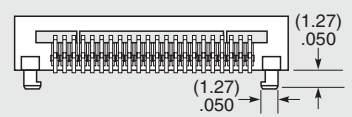
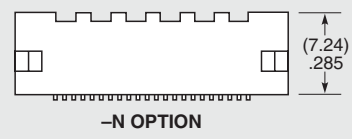
**-F**  
= Gold flash on contact, Matte Tin on tail

**-L**  
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

**CARD SLOT**

Specify CARD SLOT from chart

CARD SLOT	A	MATES WITH BOARD THICKNESS
-01	(0.97) .038	(0.80) .031
-02	(1.83) .072	(1.60) .062



**OTHER OPTION**

**-N**  
= No Card Guides

**Important Note:** Samtec recommends that pads on the mating board be Gold plated.

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.